

# Yuling Niu

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/116341/publications.pdf>

Version: 2024-02-01

21  
papers

247  
citations

1307594

7  
h-index

1588992

8  
g-index

21  
all docs

21  
docs citations

21  
times ranked

96  
citing authors

#	ARTICLE	IF	CITATIONS
1	A comprehensive solution for modeling moisture induced delamination in electronic packaging during solder reflow. <i>Microelectronics Reliability</i> , 2020, 112, 113791.	1.7	18
2	Design guideline on board-level thermomechanical reliability of 2.5D package. <i>Microelectronics Reliability</i> , 2020, 111, 113701.	1.7	8
3	Accessible determination of die-to-wafer bond strength with the Schwickerath test. <i>Engineering Fracture Mechanics</i> , 2020, 229, 106929.	4.3	1
4	Warpage Variation Analysis and Model Prediction for Molded Packages. , 2019, , .		3
5	An Accurate Experimental Determination of Effective Strain for Heterogeneous Electronic Packages With Digital Image Correlation Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2018, 8, 678-688.	2.5	10
6	The Experimental and Numerical Study of Electromigration in 2.5D Packaging. , 2018, , .		14
7	Design Guideline of 2.5D Package with Emphasis on Warpage Control and Thermal Management. , 2018, , .		29
8	Mechanical Strength Characterization of Direct Bond Interfaces for 3D-IC and MEMS Applications. , 2018, , .		2
9	Experimentally Minimizing the Gap Distance Between Extra Tall Packages and PCB Using the Digital Image Correlation (DIC) Method. , 2018, , .		8
10	Modeling and Design of 2.5D Package with Mitigated Warpage and Enhanced Thermo-Mechanical Reliability. , 2018, , .		17
11	Comprehensive Study on 2.5D Package Design for Board-Level Reliability in Thermal Cycling and Power Cycling. , 2018, , .		31
12	A comprehensive solution for electronic packages' reliability assessment with digital image correlation (DIC) method. <i>Microelectronics Reliability</i> , 2018, 87, 81-88.	1.7	21
13	A general strategy of in-situ warpage characterization for solder attached packages with digital image correlation method. <i>Optics and Lasers in Engineering</i> , 2017, 93, 9-18.	3.8	13
14	A Novel Speckle-Free Digital Image Correlation Method for In Situ Warpage Characterization. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2017, , 1-9.	2.5	13
15	An Investigation of Moisture-Induced Interfacial Delamination in Plastic IC Package During Solder Reflow. , 2017, , .		8
16	A Study on the Thermomechanical Reliability Risks of Through-Silicon-Vias in Sensor Applications. <i>Sensors</i> , 2017, 17, 322.	3.8	8
17	The Complete Packaging Reliability Studies through One Digital Image Correlation System. , 2017, , .		10
18	In-Situ Warpage Characterization of BGA Packages with Solder Balls Attached During Reflow with 3D Digital Image Correlation (DIC). , 2016, , .		14

#	ARTICLE	IF	CITATIONS
19	Die stress in stealth dicing for MEMS. , 2016, , .		6
20	A new in-situ warpage measurement of a wafer with speckle -free digital image correlation (DIC) method. , 2015, , .		11
21	An Experimental and Numerical Study of the Dynamic Fracture of Glass. , 2013, , .		2